

ADHESIVE SHEET FOR PRODUCTION OF SEMICONDUCTOR DEVICE WITH BUMP
ELECTRODE, AND METHOD FOR PRODUCTION OF SEMICONDUCTOR DEVICE

[ABSTRACT]

An adhesive sheet for production of a semiconductor device with bump electrode, including a soft film and an alkali-soluble adhesive film formed on the soft film is capable of exposing the bump electrode without imparting damage to the bump electrode, and then wet etching of an adhesive on bump tops using an aqueous alkali solution makes it possible to put into a state where no adhesive exists on the bump tops, thus enabling the production of a semiconductor device which is excellent in connection reliability after flip chip packaging.

(Fig. 1)